POWER INFRASTRUCTURE

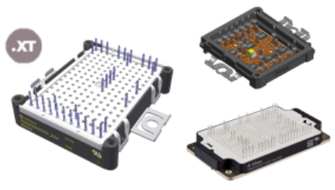
High-voltage power for next-generation AI infrastructure

AI and electrification are driving demand for high-voltage power systems that deliver greater efficiency, resilience, and scalability. Our 800 V DC protection, high-current inverter, and 3.3 kV SiC power solutions showcase packaging innovations that increase reliability, power density, and cost efficiency.

Benefits
- Best-in-class power cycling capability
- .XT industry-leading operating temperature at 200°C (prev. 175°C)
- .XT copper metallization and bondwire for superior die interconnection
- Higher power density and system efficiency
- Simplified system integration and design scalability

Highlight products
- .XT interconnection technology
- CoolSiC™ power modules
- Pressure-contact power modules
- EasyPACK™ platform solutions

Applications
- AI data centers
- DC power distribution
- Energy storage systems
- Solid-state transformers
- Industrial infrastructure

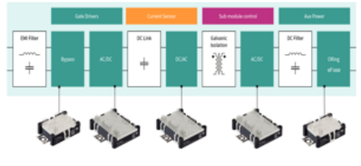


SiC Power Modules for AI Power Infrastructure with .XT Interconnection Technology

55kW NPC2 Demo Board based on 350A IGBT H7 in DTO Package



EasyPACK™ power modules for solid-state transformers





Decoupling diode for 800V DC grid for data centers

Scan for more information